PROPERTIES OF THREE LAYER PARTICLEBOARD FROM KELEMPAYAN

(*Neolamarckia cadamba*)

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ABSTRACT

PROPERTIES OF THREE LAYER PARTICLEBOARD FROM KELEMPAYAN

(\textit{Neolamarckia cadamba})

Particleboard is a panel product made by compressing small particles of wood while simultaneously bonding them with an adhesive. The objective of the study to investigate the mechanical and physical properties of three layer particleboard from Kelempayan (\textit{Neolamarckia cadamba}) at different proportion level and properties were evaluated based on Japanese Industrial Standard. Variables factor were as density (500 kg/m$^3$, 600 kg/m$^3$ and 700 kg/m$^3$) and resin content of urea formaldehyde (8\%, 10\% and 12\%). The mechanical and physical properties were presented and analyzed using Software Package Used for Statistical Analysis (SPSS) to determine the significant different of variables. The result collected shows that all the variables for mechanical properties were significant different and the better result was 700 kg/m$^3$ of density when using 12\% of resin content. For physical properties, the strength of board decrease since the board has no water repellent.
# TABLE OF CONTENT

<table>
<thead>
<tr>
<th>Section</th>
<th>Pages</th>
</tr>
</thead>
<tbody>
<tr>
<td>DEDICATIONS</td>
<td>iii</td>
</tr>
<tr>
<td>ACKNOWLEDGEMENT</td>
<td>iv</td>
</tr>
<tr>
<td>TABLE OF CONTENTS</td>
<td>v</td>
</tr>
<tr>
<td>LIST OF TABLES</td>
<td>vii</td>
</tr>
<tr>
<td>LIST OF FIGURES</td>
<td>viii</td>
</tr>
<tr>
<td>LIST OF ABBREVIATION</td>
<td>ix</td>
</tr>
<tr>
<td>ABSTRACT</td>
<td>x</td>
</tr>
<tr>
<td>ABSTRAK</td>
<td>xi</td>
</tr>
</tbody>
</table>

## 1.0 INTRODUCTION

1.1 General 1
1.2 Problem statements 3
1.3 Justification 4
1.4 Objective 4

## 2.0 LITERATURE REVIEW

2.1 Particle Composite 5
2.1.1 History and Development 6
2.1.2 Application and Market Distribution 8
2.1.3 Raw Material Specification 9
2.2 Kelempanyan Species 10
2.3 Urea Formaldehyde 11
2.4 Effect of density on particleboard 12
2.5 Effect of resin content on particleboard 12
3.0 MATERIAL AND METHOD

3.1 Raw Material Preparation 14
3.2 Particleboard Manufacturing 15
3.3 Panel Testing 17
   3.3.1 Density 17
   3.3.2 Bending Strength 18
   3.3.3 Internal Bonding 19
   3.3.4 Thickness Swelling and Water Absorption 19
3.4 Experimental Design 20
3.5 Statistical Analyzed 21

4.0 RESULT AND DISCUSSION

4.1 Mechanical and Physical Properties of Particleboard 22
   4.1.1 Effect Density On Mechanical Properties 23
   4.1.2 Effect Density On Physical Properties 25
   4.1.3 Effect Resin Content On Mechanical Properties 27
   4.1.4 Effect Resin Content On Physical Properties 29

5.0 CONCLUSION

5.1 Conclusions 31

REFERENCES 33
APPENDICES 36
CURRICULUM VITAE 69
# LIST OF FIGURES

<table>
<thead>
<tr>
<th>Figure</th>
<th>Caption</th>
<th>Pages</th>
</tr>
</thead>
<tbody>
<tr>
<td>3.1</td>
<td>Schematic diagrams of panel cutting</td>
<td>16</td>
</tr>
<tr>
<td>3.2</td>
<td>Experimental design of study</td>
<td>20</td>
</tr>
<tr>
<td>4.1</td>
<td>Effect of density on mechanical properties</td>
<td>23</td>
</tr>
<tr>
<td>4.2</td>
<td>Effect of density on physical properties</td>
<td>25</td>
</tr>
<tr>
<td>4.3</td>
<td>Effect of resin content on mechanical properties</td>
<td>27</td>
</tr>
<tr>
<td>4.4</td>
<td>Effect of resin content on physical properties</td>
<td>29</td>
</tr>
</tbody>
</table>